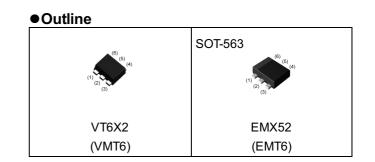


## Power management (dual transistors)

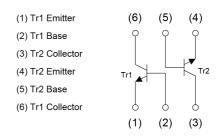
Datasheet

Parameter	Tr1 and Tr2
V <sub>CEO</sub>	50V
۱ <sub>C</sub>	100mA



## Features

- 1) General Purpose.
- 2) Two 2SAR523 chips in one package.
- Transister elements are independent, eliminating interface.
- 4) Mounting cost and area can be cut in half.



Inner circuit

## Application

SWITCH, LED DRIVER

## Packaging specifications

Part No.	Package	Package size	Taping code	Reel size (mm)	Tape width (mm)	Basic ordering unit.(pcs)	Marking
VT6X2	(VMT6)	1212	T2R	180	8	8000	X2
EMX52	SOT-563 (EMT6)	1616	T2R	180	8	8000	X52

## • Absolute maximum ratings (T<sub>a</sub> = 25°C)

<It is the same ratings for the Tr1 and Tr2>

P	arameter	Symbol	Values	Unit
Collector-base voltage		V <sub>CBO</sub>	50	V
Collector-emitter voltage		V <sub>CEO</sub>	50	V
Emitter-base voltage		V <sub>EBO</sub>	5	V
Collector current		Ι <sub>C</sub>	100	mA
		I <sub>CP</sub> *1	200	mA
Power dissipation	VT6X2	D *2*3	150	
	EMX52	P <sub>D</sub> <sup>*2*3</sup>	150	— mW
Junction temperature		Tj	150	°C
Range of storage temperature		T <sub>stg</sub>	-55 to +150	°C

## • Electrical characteristics (T<sub>a</sub> = 25°C)

< It is the same characteristics for the Tr1 and Tr2>

Deremeter	Cumphal	vmbol Conditions Values		Values		Unit	
Parameter	Symbol	Conditions	Min.	Min. Typ. Max.			
Collector-base breakdown voltage	BV <sub>CBO</sub>	Ι <sub>C</sub> = 50μΑ	50	-	-	V	
Collector-emitter breakdown voltage	$BV_{CEO}$	I <sub>C</sub> = 1mA	50	-	-	V	
Emitter-base breakdown voltage	$BV_{EBO}$	Ι <sub>Ε</sub> = 50μΑ	5	-	-	V	
Collector cut-off current	$I_{CBO}$ $V_{CB} = 50V$		I	-	100	nA	
Emitter cut-off current I <sub>EBO</sub>		V <sub>EB</sub> = 5V	-	-	100	nA	
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$_{E(sat)}$ I <sub>C</sub> = 50mA, I <sub>B</sub> = 5mA		100	300	mV	
DC current gain	h <sub>FE</sub>	$V_{CE} = 6V, I_C = 1mA$		-	560	-	
Transition frequency	f⊤	$f_{T}$ $V_{CE} = 10V, I_{E} = -10mA, f = 100MHz$		350	-	MHz	
Output capacitance	C <sub>ob</sub>	V <sub>CB</sub> = 10V, I <sub>E</sub> = 0A, f = 1MHz	-	1.6	-	pF	

2/7

\*1 Pw=10ms Single Pulse

\*2 Each terminal mounted on a reference land.

\*3 120mW per element must not be exceeded.

<For Tr1 and Tr2 in common>



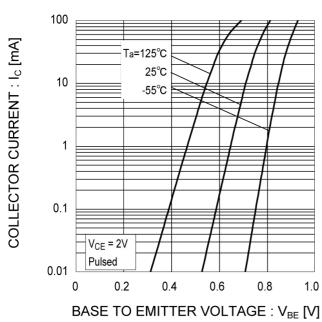


Fig.3 DC Current Gain vs. Collector Current (I)

ТШ

1

COLLECTOR CURRENT : Ic [mA]

Ta=125°C 25°C -55°C

1000

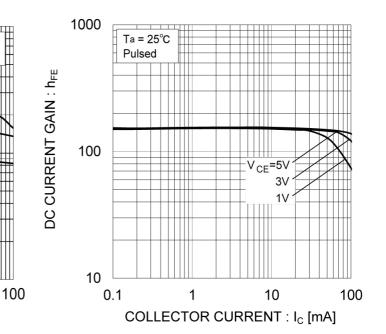
100

10

0.1

DC CURRENT GAIN : hFE

Fig.4 DC Current Gain vs. Collector Current (II)



## Fig.2 Typical Output Characteristics

450μΑ 400μΑ

500µA

50

40

30

20

10

COLLECTOR CURRENT : I<sub>c</sub> [mA]

1.0

 $V_{CE} = 5V$ 

Pulsed

10

IB=0A 0 1 2 3 0 4 5 COLLECTOR TO EMITTER VOLTAGE : V<sub>CE</sub> [V]

Ta = 25°C Pulsed



350µA

300µA

250μΑ

200µA

150µA

100µA

50µA

100

## • Electrical characteristic curves (T<sub>a</sub> = 25°C)

<For Tr1 and Tr2 in common>

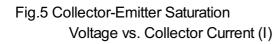


Fig.6 Collector-Emitter Saturation Voltage vs. Collector Current (II) 1  $Ta = 25^{\circ}C$ Pulsed

 $|_{C}/|_{B} = 20$ 

10

10

COLLECTOR CURRENT : Ic [mA]

0.1

1

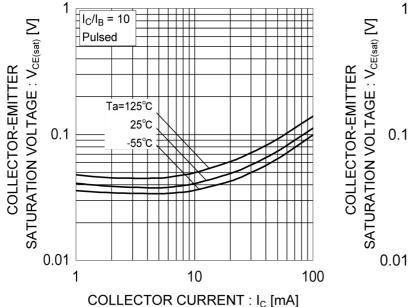
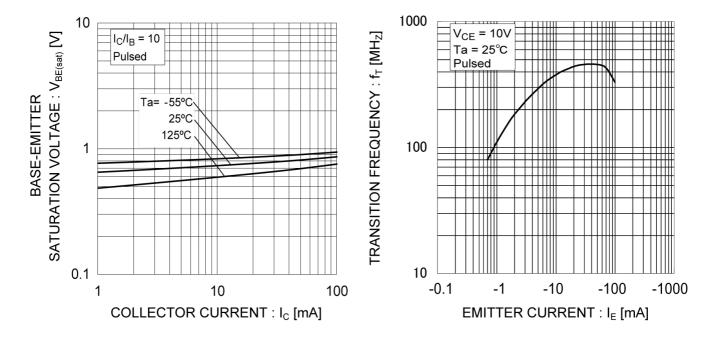


Fig.7 Base-Emitter Saturation Voltage vs. Collector Current

Fig.8 Gain Bandwidth Product vs. **Emitter Current** 

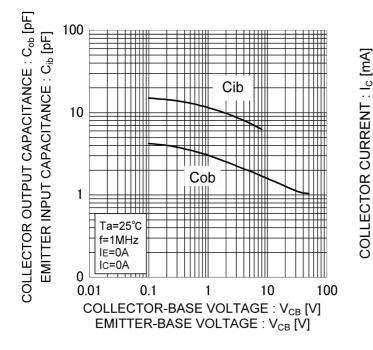




## •Electrical characteristic curves (T<sub>a</sub> =25°C)

<For Tr1 and Tr2 in common>

Fig.9 Emitter Input Capacitance vs. Emitter-Base Voltage Collector Output Capacitance vs. Collector-Base Voltage



1000 VT6X2 100 1ms HH 10ms DC (Mounted on a reference land) 100ms 10 Ta=25 °C Single non repetitive pulse. Single element at operation. 1 0.1 100 1 10 COLLECTOR TO EMITTER VOLTAGE : V<sub>CE</sub> [V]

Fig.11 Safe Operating Area

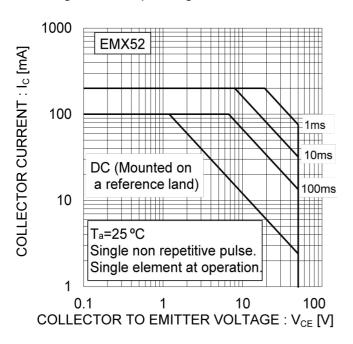
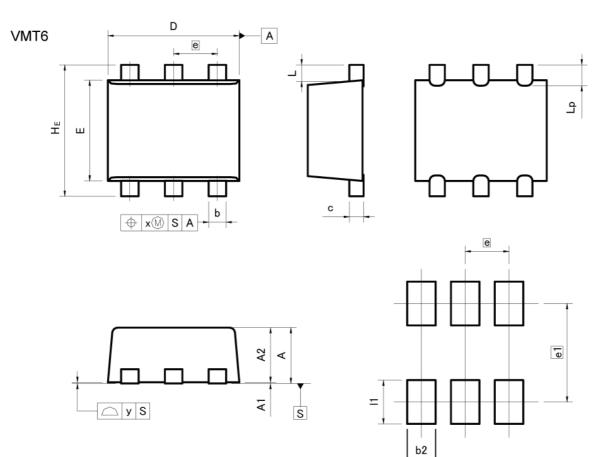


Fig.10 Safe Operating Area



## Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

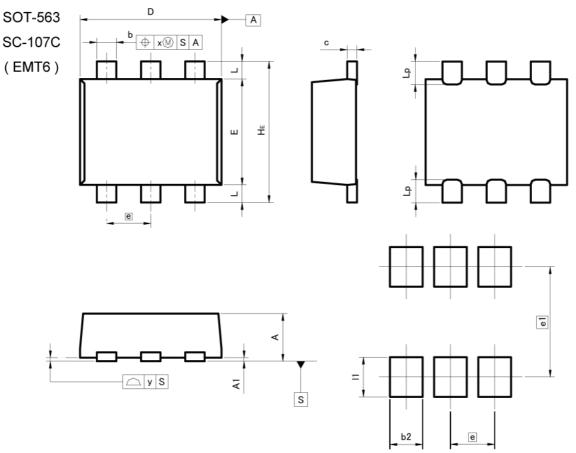
DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
А	0.45	0.55	0.018	0.022
A1	0.00	0.05	0.000	0.002
A2	0.40	0.60	0.016	0.024
b	0.11	0.21	0.004	0.008
С	0.08	0.18	0.003	0.007
D	1.152	1.248	0.045	0.049
Е	0.82	1.02	0.032	0.04
е	0.4	0.40		16
HE	1.152	1.248	0.045	0.049
L	0.	0.14		06
Lp	0.10	0.30	0.004	0.012
x	-	0.05	-	0.002
У	-	0.10	-	0.004

DIM	MILIM	ETERS	INCHES		
DIN	MIN	MAX	MIN	MAX	
b2	_	0.26	—	0.010	
e1	0.9	90	0.0	35	
1	- 0.40		-	0.016	

Dimension in mm/inches



## Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIMETERS		INCHES		
DIM	MIN	MAX	MIN	MAX	
A	0.45	0.55	0.018	0.022	
A1	0.00	0.10	0.000	0.004	
b	0.17	0.27	0.007	0.011	
с	0.08	0.18	0.003	0.007	
D	1.50	1.70	0.059	0.067	
E	1.10	1.30	0.043	0.051	
е	0.50		0.0	20	
HE	1.50	1.70	0.059	0.067	
L	0.10	0.30	0.004	0.012	
Lp	-	0.35	-	0.014	
x	-	0.10	-	0.004	
У		0.10	-	0.004	
DIM	MILIMETERS		INC	HES	
DIM	MIN	MAX	MIN	MAX	
b2	-	0.37	-	0.015	
e1	1.25		0.049		
1	-	0.45	-	0.018	

Dimension in mm/inches



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(Note1) Medical Equipment Classification of the Specific Applications
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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	
CLASSⅣ	CLASSII	CLASSⅢ	CLASSII

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  - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
  - [C] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

#### **Precaution for Storage / Transportation**

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
  - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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